

Title (en)
FLUX FOR RESIN FLUX CORED SOLDERS, FLUX FOR FLUX COATED SOLDERS, RESIN FLUX CORED SOLDER AND FLUX COATED SOLDER

Title (de)
FLUSSMITTEL FÜR HARZFLUSSMITTELGEFÜLLTES LOT, FLUSSMITTEL FÜR FLUSSMITTELBESCHICHTETES LOT, HARZFLUSSMITTELGEFÜLLTES LOT UND FLUSSMITTELBESCHICHTETES LOT

Title (fr)
FLUX DESTINÉ À DES SOUDURE À ÂME DÉCAPANTE DE FLUX RÉSINEUX, FLUX DESTINÉ À DES SOUDURES À ÂME DÉCAPANTE DE FLUX, ET SOUDURE RECOUVERTE DE FLUX

Publication
EP 3456460 A4 20190807 (EN)

Application
EP 17909653 A 20171227

Priority

- JP 2017112459 A 20170607
- JP 2017046832 W 20171227

Abstract (en)
[origin: EP3456460A1] An object of the present invention is to provide a resin flux cored solder, or a flux coated solder, for which scattering of flux and solder in using the solder is suppressed, and a flux to be contained therein. A flux for a resin flux cored solder comprising a rosin resin, an activator, and at least one selected from an acrylic polymer and a vinyl ether polymer, which has a weight average molecular weight of 8000 to 100000, in an amount of 0.1 to 3 mass-% based on the total mass of the flux.

IPC 8 full level
B23K 35/36 (2006.01); **B23K 35/02** (2006.01); **B23K 35/14** (2006.01); **B23K 35/362** (2006.01); **B23K 35/365** (2006.01); **B23K 35/368** (2006.01); **B23K 35/40** (2006.01); **B23K 35/26** (2006.01); **C22C 13/00** (2006.01)

CPC (source: EP KR US)
B23K 35/0222 (2013.01 - KR); **B23K 35/0227** (2013.01 - EP US); **B23K 35/0266** (2013.01 - EP US); **B23K 35/262** (2013.01 - US); **B23K 35/3613** (2013.01 - EP KR US); **B23K 35/362** (2013.01 - EP KR US); **B23K 35/365** (2013.01 - EP US); **B23K 35/368** (2013.01 - EP US); **B23K 35/404** (2013.01 - EP US); **B23K 35/406** (2013.01 - EP US); **B23K 35/262** (2013.01 - EP); **C22C 13/00** (2013.01 - EP)

Citation (search report)

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- [A] US 2008053572 A1 20080306 - SANJI MASAKI [JP], et al
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- [A] JP 2015131336 A 20150723 - TAMURA SEISAKUSHO KK
- See references of WO 2018225288A1

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

DOCDB simple family (publication)
EP 3456460 A1 20190320; EP 3456460 A4 20190807; EP 3456460 B1 20210331; BR 112018076173 A2 20200204; BR 112018076173 B1 20201103; CN 109641324 A 20190416; CN 109641324 B 20200925; DK 3456460 T3 20210510; ES 2876123 T3 20211111; HU E054993 T2 20211028; JP 2018202465 A 20181227; JP 6268507 B1 20180131; KR 101986264 B1 20190605; KR 20180134326 A 20181218; MX 2018015086 A 20190513; PH 12018502493 A1 20190715; PH 12018502493 B1 20190715; PL 3456460 T3 20211011; TW 201902608 A 20190116; TW I641442 B 20181121; US 10688603 B2 20200623; US 2019358753 A1 20191128; WO 2018225288 A1 20181213

DOCDB simple family (application)
EP 17909653 A 20171227; BR 112018076173 A 20171227; CN 201780005681 A 20171227; DK 17909653 T 20171227; ES 17909653 T 20171227; HU E17909653 A 20171227; JP 2017046832 W 20171227; JP 2017112459 A 20170607; KR 20187019308 A 20171227; MX 2018015086 A 20171227; PH 12018502493 A 20181126; PL 17909653 T 20171227; TW 106143980 A 20171214; US 201716304099 A 20171227